

Low $V_{CE(sat)}$ PNP Epitaxial Planar Transistor

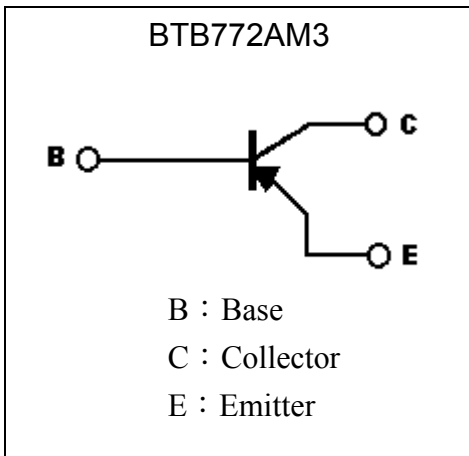
BTB772AM3

BV_{CEO}	-50V
I_C	-3A
$R_{CESAT(typ)}$	0.12 Ω

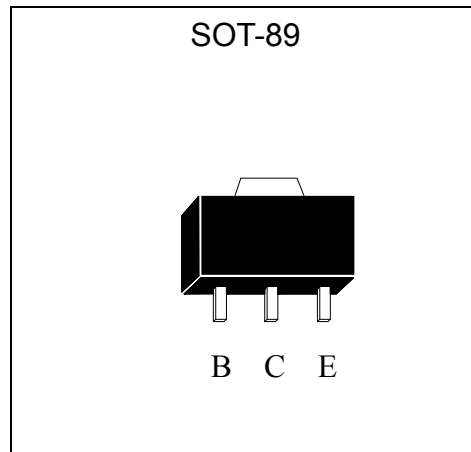
Features

- Low $V_{CE(sat)}$, typically -0.24 V at $I_C / I_B = -2A / -0.2A$
- Excellent current gain characteristics
- Complementary to BTD882AM3
- Pb-free lead plating and halogen-free package

Symbol

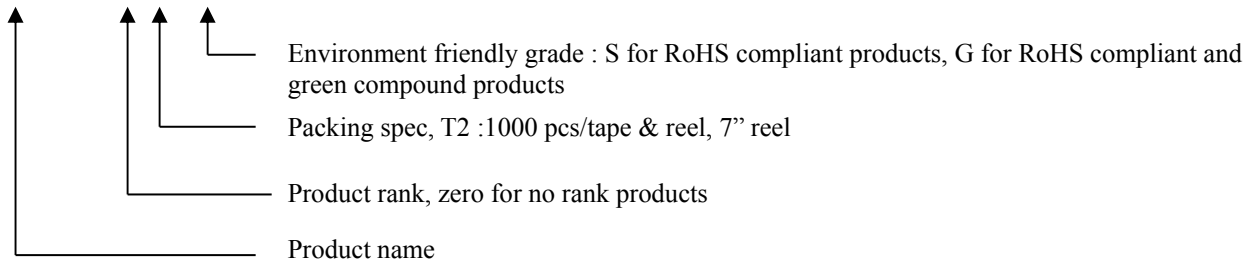


Outline



Ordering Information

Device	Package	Shipping
BTB772AM3-X-T2-G	SOT-89 (Pb-free lead plating and halogen-free package)	1000 pcs / Tape & Reel





Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CB0}	-50	V
Collector-Emitter Voltage	V _{CE0}	-50	V
Emitter-Base Voltage	V _{EB0}	-6	V
Collector Current (DC)	I _C	-3	A
Collector Current (Pulse)	I _{CP}	-7 (Note 1)	A
Power Dissipation	P _d	600	mW
		1 (Note 2)	W
		2 (Note 3)	W
Thermal Resistance, Junction to Ambient	R _{θJA}	208	°C/W
		125 (Note 2)	°C/W
		62.5 (Note 3)	°C/W
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55~+150	°C

- Note : 1. Single Pulse Pw ≤ 350μs, Duty ≤ 2%.
 2. When mounted on a FR-4 PCB with area measuring 10×10×1 mm.
 3. When Mounted on a ceramic board with area measuring 40×40×1mm.

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	-50	-	-	V	I _C =-50μA, I _E =0
BV _{CE0}	-50	-	-	V	I _C =-1mA, I _B =0
BV _{EB0}	-6	-	-	V	I _E =-50μA, I _C =0
I _{CB0}	-	-	-1	μA	V _{CB} =-40V, I _E =0
I _{EB0}	-	-	-1	μA	V _{EB} =-5V, I _C =0
*V _{CE(sat)}	-	-0.24	-0.5	V	I _C =-2A, I _B =-0.2A
*V _{BE(sat)}	-	-1	-2	V	I _C =-2A, I _B =-0.2A
*h _{FE1}	120	-	-	-	V _{CE} =-2V, I _C =-20mA
*h _{FE2}	180	-	560	-	V _{CE} =-2V, I _C =-500mA
*h _{FE3}	100	-	-	-	V _{CE} =-2V, I _C =-1A
f _T	-	80	-	MHz	V _{CE} =-5V, I _C =-0.1A, f=100MHz
C _{ob}	-	25	-	pF	V _{CB} =-10V, f=1MHz

*Pulse Test : Pulse Width ≤ 380μs, Duty Cycle ≤ 2%

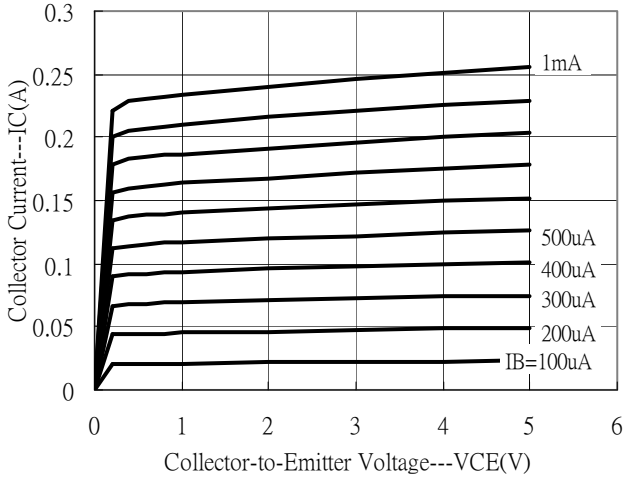
Classification Of h_{FE2}

Rank	R	S
Range	180~390	270~560

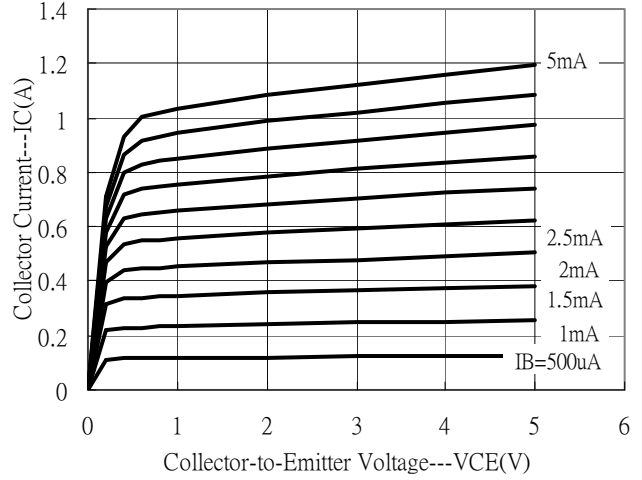


Typical Characteristics

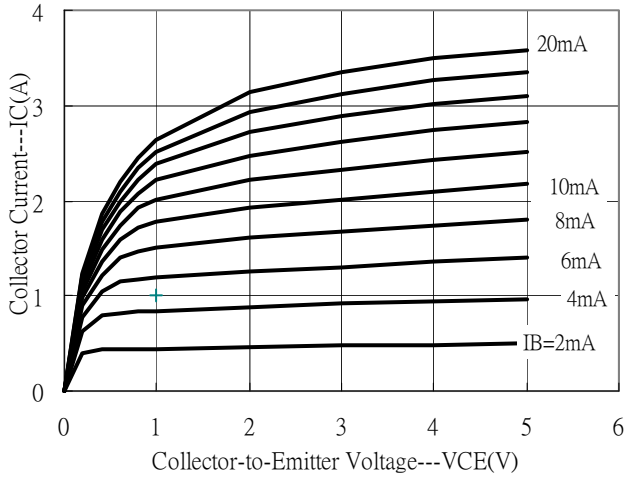
Emitter Grounded Output Characteristics



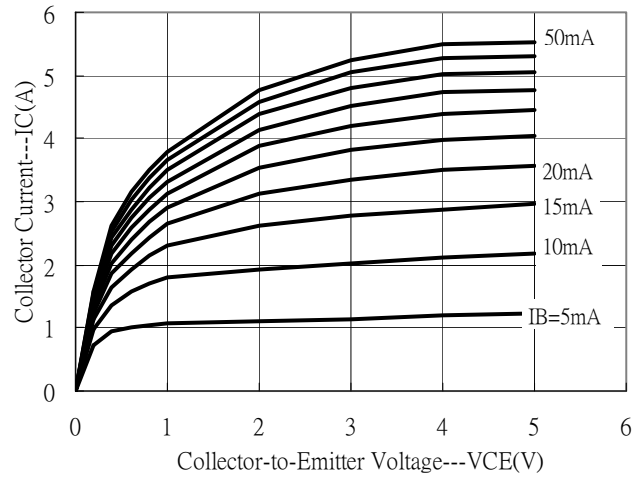
Emitter Grounded Output Characteristics



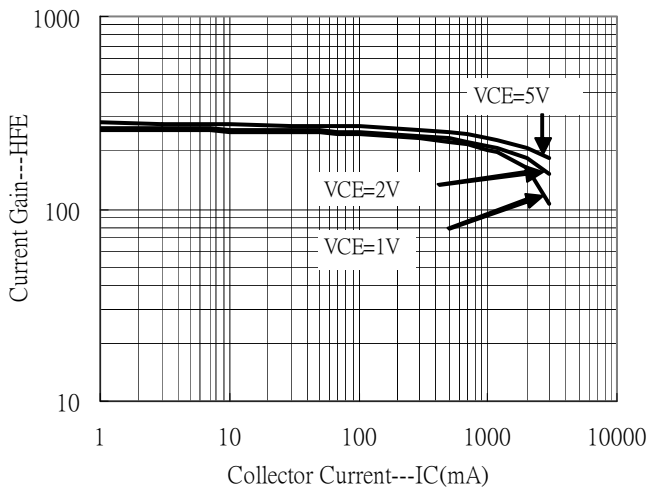
Emitter Grounded Output Characteristics



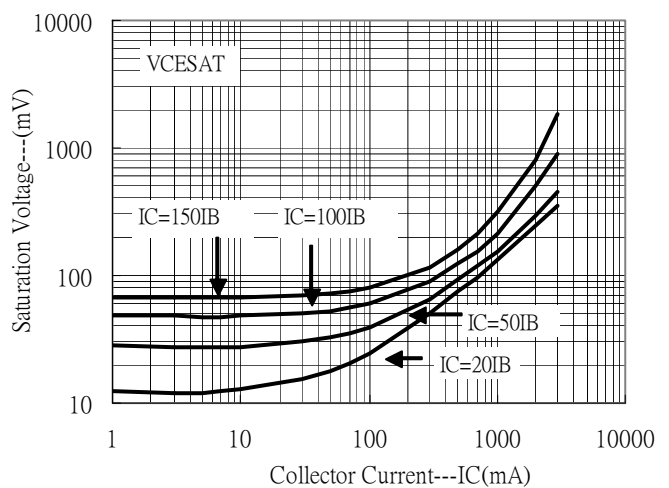
Emitter Grounded Output Characteristics



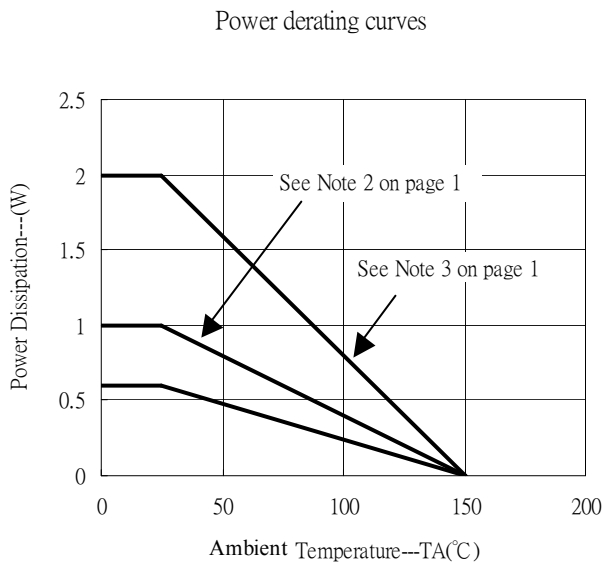
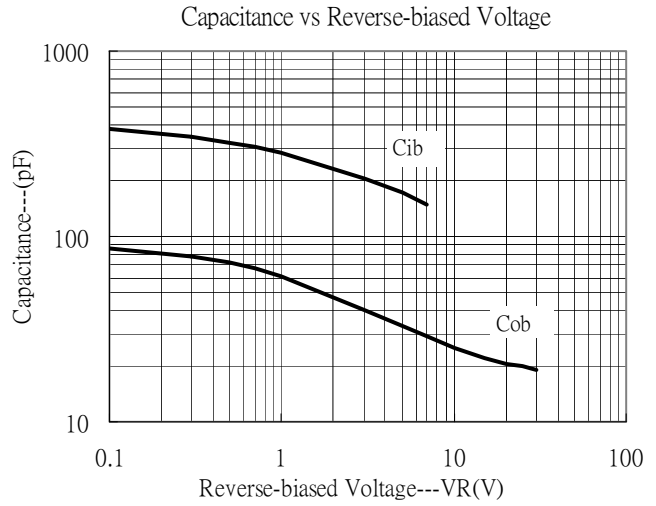
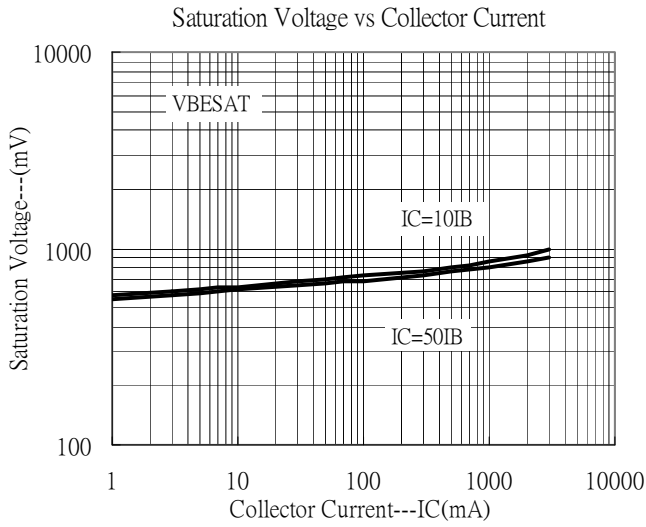
Current Gain vs Collector Current



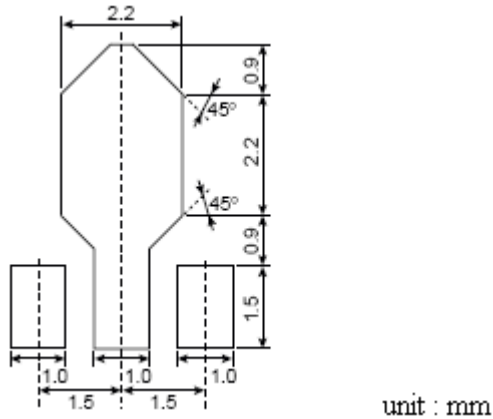
Saturation Voltage vs Collector Current



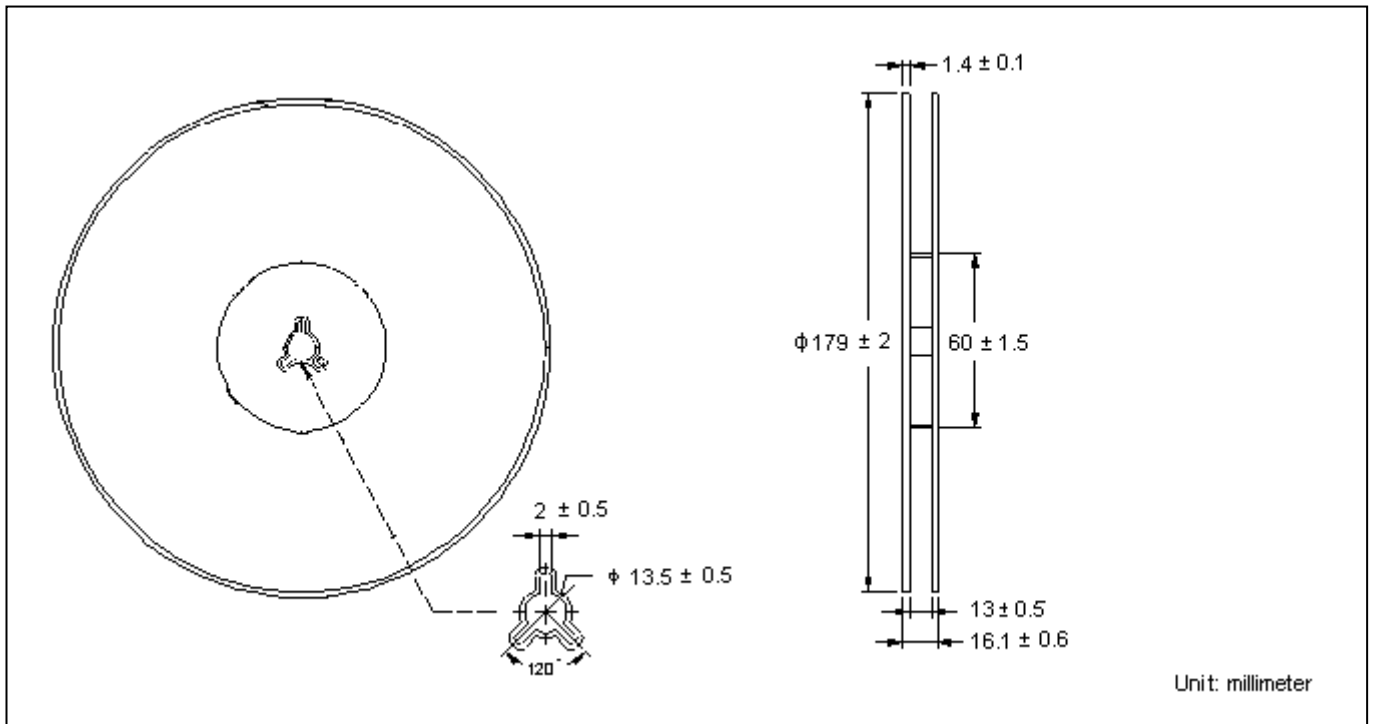
Typical Characteristics(Cont.)



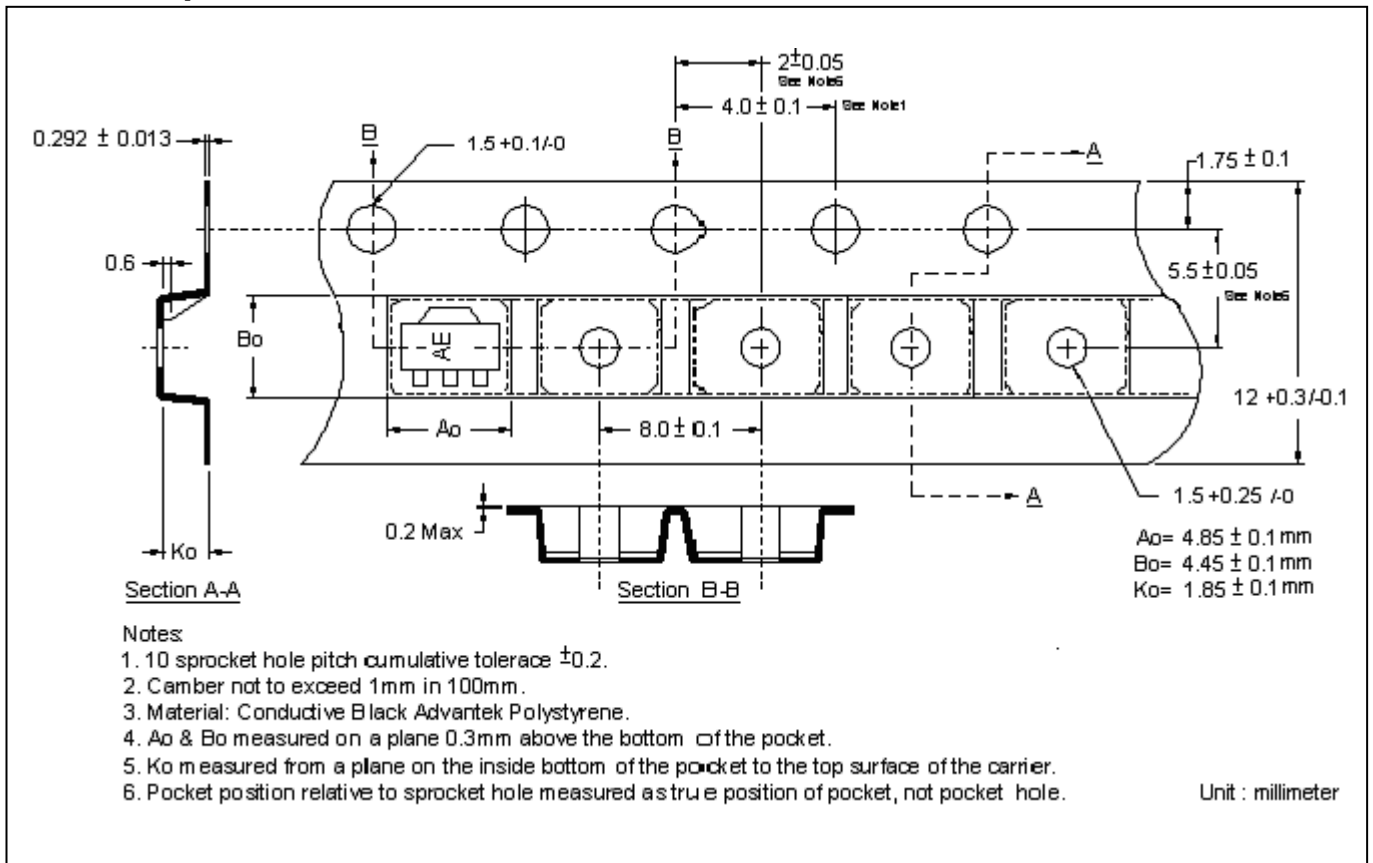
Recommended soldering footprint



Reel Dimension



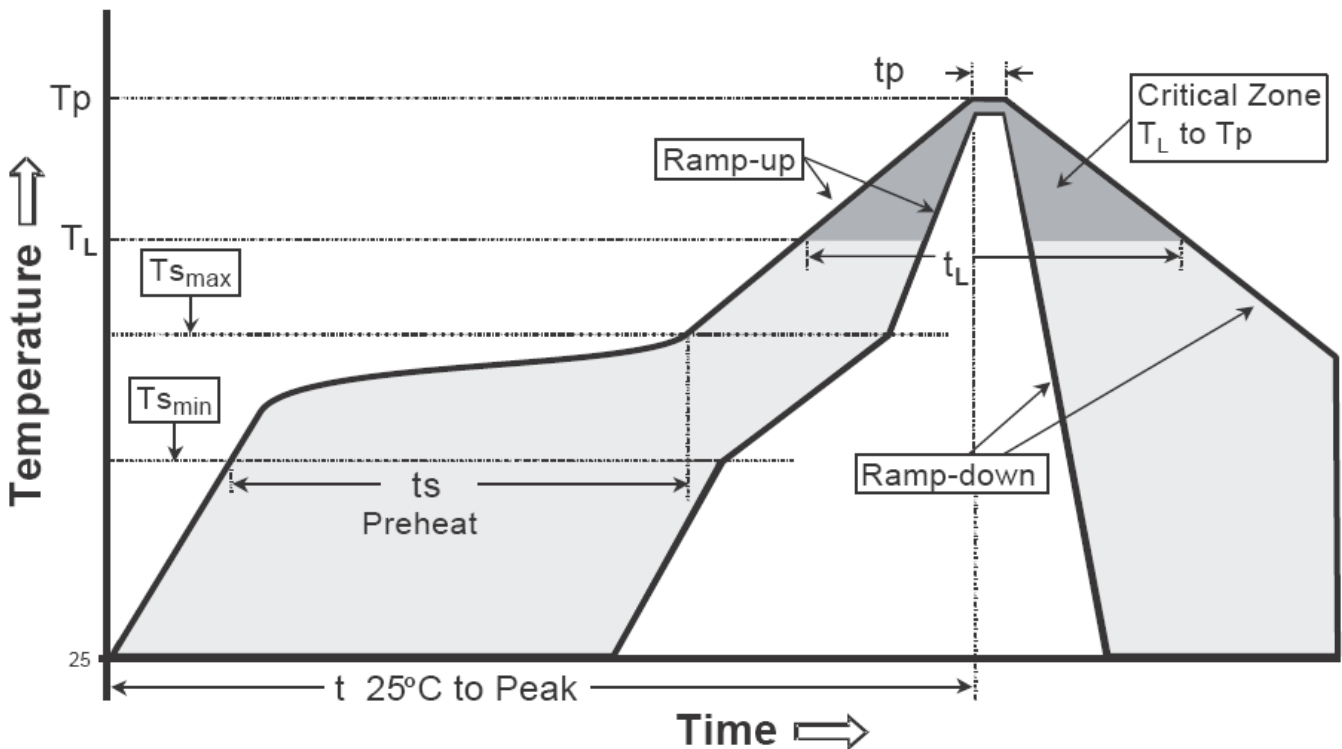
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

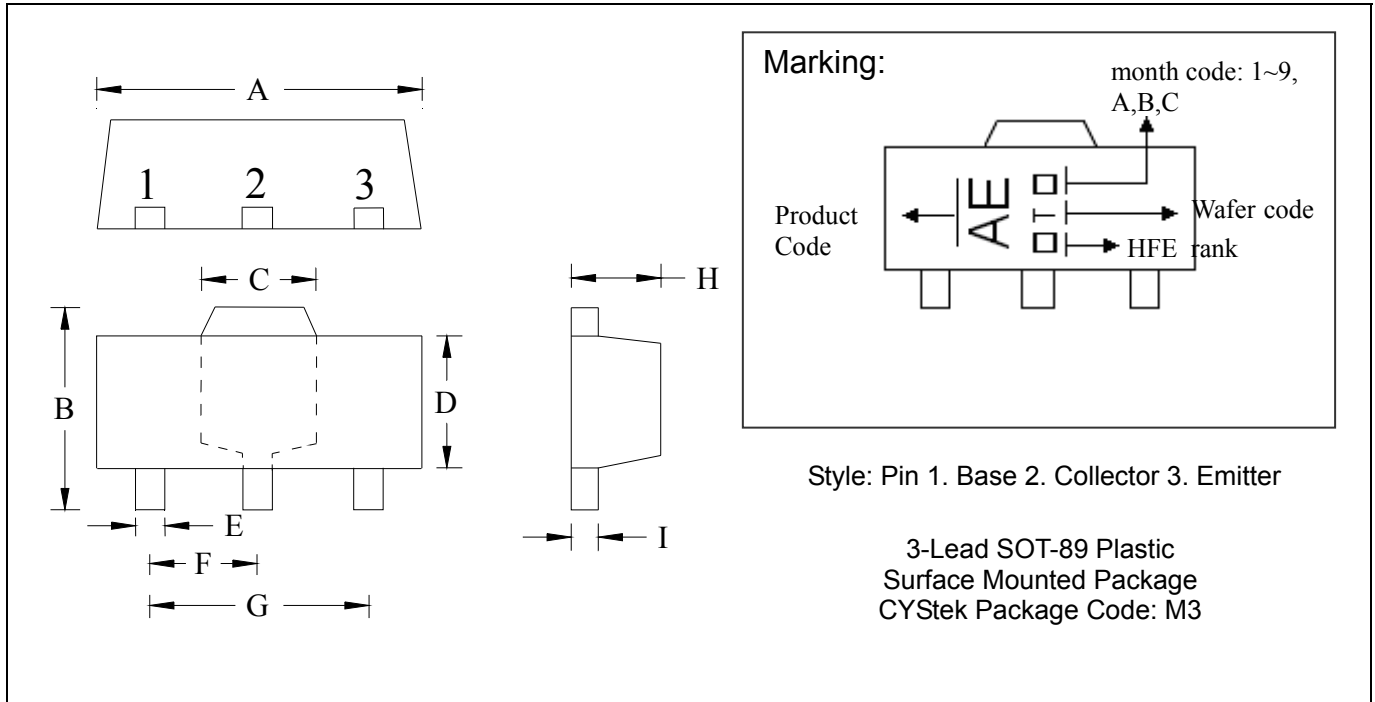
Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(t _p)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-89 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0591	TYP	1.50	TYP
B	0.1551	0.1673	3.94	4.25	G	0.1181	TYP	3.00	TYP
C	0.0610	REF	1.55	REF	H	0.0551	0.0630	1.40	1.60
D	0.0906	0.1024	2.30	2.60	I	0.0138	0.0173	0.35	0.44
E	0.0126	0.0205	0.32	0.52					

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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